Tool ID: 301
Tool Location: 103

Equipment Information Sheet

Oxford ALD FlexAL

Manager: Jeremy Clark 607-254-6487
Backup: Philip Schneider 607-254-4931

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- The FlexAL ALD tool uses toxic and highly reactive/pyrophoric precursors for film deposition. Materials are monitored by the Toxic Gas Monitoring and Control System that will sound a gas alarm in the event of a detection.

USAGE RESTRICTIONS

- Run the recipe "3min end of use clean" once you are finished processing.

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 60 minutes

- None

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No films thicker than 50nm or 500 loops without permission of the tool managers
- No changing of recipes other than loop count without permission of the tool managers
- Full size 100mm wafers (other wafer sizes up to 200mm can be accommodated with staff assistance).
- Pieces can be processed with the use of the dedicated Aluminum carrier plate.
- Polymers and resist need to be fully cured and only run using 110C processes

Last Updated: 04/30/2026